

COPPER FOIL FOR FINE PATTERN PRINTED CIRCUITS AND METHOD  
OF PRODUCTION OF SAME

ABSTRACT OF THE DISCLOSURE

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Copper foil for fine pattern printed circuits having a sufficient bond strength with a resin substrate, eliminating the problems of residual copper, erosion at the bottom portions of the circuit lines, etc. at the 10 time of formation of fine patterns, and superior in heat resistance and electrical characteristics, comprising untreated copper foil roughening treated on its surface, wherein the untreated copper foil before roughening treatment is an electrodeposited copper foil having a 15 surface roughness in terms of 10-point average roughness Rz not more than 2.5  $\mu\text{m}$  and a minimum distance between peaks of rough pyramid of at least 5  $\mu\text{m}$  or having further crystal grains of an average particle size of not more than 2  $\mu\text{m}$  exposed at the surface thereof, and a method of 20 production of the same.